

View Online at <https://aerobasegroup.com/nsn/5910-01-386-9491>

**Body Style:**

Chip type

**Reliability Indicator:**

Established

**Reliability Failure Rate Level In Percent:**

0.001

**Terminal Length:**

Between 1.0 millimeters and 1.6 millimeters

**Body Length:**

Between 7.0 millimeters and 7.6 millimeters

**Body Width:**

3.1 millimeters

**Body Height:**

Between 4.0 millimeters and 4.6 millimeters

**Schematic Diagram Designator:**

No common or grounded electrode (s)

**Electrical Polarization:**

Nonpolarized

**Capacitance Value Per Section:**

33.000 microfarads single section

**Nonderated Operating Temp:**

Between -55.0 degrees celsius and 125.0 degrees celsius

**Dc Leakage At Maximum Operating Temp:**

39.6 microamperes

**Nonderated Continuous Voltage Rating And Type Per Section:**

10.0 dc single section

**Tolerance Range Per Section:**

-5.00/+5.00 percent single section

**Case Material:**

Ceramic

**Capacitive Electrode Material:**

Tantalum

**Dissipation Factor At Reference Temperature In Percent:**

6.000

**Equivalent Series Resistance At Reference Temperature In Ohms:**

1.80

**Dc Leakage At Reference Temp:**

3.300 microamperes

**Terminal Surface Treatment:**

Solder

**Test Data Document:**

81349-mil-c-55365 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

**Terminal Type And Quantity:**

2 bonding pad

**Specification Data:**

81349-mil-c-55365/8 government specification

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

No

**Fiig:**

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